

**MARK-UP PAGES FOR THE JUNE 27, 2002, AMENDMENT TO
U.S. PATENT APPLICATION SER. NO. 09/823,600**

The replacement for claim 1 resulted from the following changes:

--Claim 1. (amended) A die attach package for connecting a die-down die in a die-up orientation, the die-down die attach package comprising:

a substrate having a plurality of leads for connection to the die-down die and to a printed circuit board,

means to physically connect the die to said substrate, wherein said means is electrically non-conductive; and

a plurality of connectors corresponding in number to the number of leads, wherein said connectors electrically connect the die to said leads, wherein said leads are arranged as part of said substrate such that they pass under the die when the die is connected to said substrate; wherein the leads on the substrate terminate at points that correspond to a die-up orientation.